

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

29-JUN-2004

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #13513

TITLE: Initial PCN for Qualification of VHVIC Sot-223 Products at ON Semiconductor, Seremban, Malaysia

EFFECTIVE DATE: 29-OCT-2004

AFFECTED CHANGE CATEGORY:

ON Semiconductor Assembly Site

AFFECTED PRODUCT DIVISION: Analog Products Div

ADDITIONAL RELIABILITY DATA: None

SAMPLES: No

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or HECTOR CORLETO, R42198@onsemi.com >

DISCLAIMER:

Initial Product/Process Change Notification (IPCN) -

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is the Initial Product Change Notification announcing ON Semiconductor's internal assembly site in Seremban, Malaysia, is being qualified to assemble ON Semiconductor's VHVIC SOT-223 products for increased capacity. These products are currently assembled at PSI Technologies in Manila, Philippines. Parts may be assembled at either of these sites after the effectivity date of the Final PCN, which will be issued upon completion of reliability testing.

Devices will continue to meet all Data Book Specifications, and reliability will continue to meet or exceed ON Semiconductor standards.

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QUALIFICATION PLAN:

HTB 150C 1008 hrs 3x80	ze
HTBB 125C, 600V 1008 hrs 3x80	
PC MSL1, 235C (for HAST, UHAST, TC)	
PC-HAST 130C, 85%RH 96hrs 3x80	
PC-UHAST 130C, 85%RH 96hrs 3x80	
PC-TC -65C to 150C 500cyc 3x80	
Bond Pull Strength 3x5	
Bond Shear 3x5	
Die Shear Strength 3x5	
X-ray 3x10	

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AFFECTED DEVICE LIST (WITHOUT SPECIALS):

PART

NCP1010ST100T3

NCP1010ST130T3

NCP1010ST65T3

NCP1011ST100T3

NCP1011ST130T3

NCP1011ST65T3

NCP1012ST100T3

NCP1012ST130T3

NCP1012ST65T3

NCP1012XST100T3

NCP1013ST100T3

NCP1013ST130T3

NCP1013ST65T3

NCP1014ST100T3

NCP1014ST65T3

NCP1050ST100T3

NCP1050ST136T3

NCP1050ST44T3

NCP1051ST100T3

NCP1051ST136T3

NCP1051ST44T3

NCP1052ST100T3

NCP1052ST136T3

NCP1052ST44T3

NCP1053ST100T3

NCP1053ST136T3

NCP1053ST44T3

NCP1054ST100T3

NCP1054ST136T3

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NCP1055ST136T3

NCP1055ST44T3

PCP1052ST44T3

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